



## Material Content Data Sheet



<b>Sales Product Name</b>		ISP752T		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA001056432						
<b>Package</b>		PG-DSO-8-24		<b>Weight*</b>		83.28 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.188	2.63	2.63	26276	26276
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		431	
	non noble metal	iron	7439-89-6	0.717	0.86		8612	
wire	non noble metal	copper	7440-50-8	29.121	34.97	35.88	349687	358838
	noble metal	gold	7440-57-5	0.372	0.45	0.45	4465	4465
	encapsulation	organic material	carbon black	1333-86-4	0.097	0.12		1168
plastics	plastics	epoxy resin	-	4.474	5.37		53720	
	inorganic material	silicondioxide	60676-86-0	44.056	52.89	58.38	529023	583911
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9773	9773
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7808	7808
glue	plastics	epoxy resin	-	0.130	0.16		1563	
	noble metal	silver	7440-22-4	0.613	0.74	0.90	7366	8929
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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